



Intel® Solid-State Drive Data Center Family for PCIe* Non-Volatile Memory Storage Solutions

PRODUCT BRIEF

Consistently Amazing

Premier Performance, Protection, and Optimization for the Data Center

The Intel® Solid-State Drive Data Center Family for PCIe* provides breakthrough performance to modernize data center storage from an industry leader.



Breakthrough Performance

Servers can now support more users simultaneously, compute on larger data sets, and address high-performance computing at lower Total Cost of Ownership (TCO).

The Intel® Solid-State Drive (SSD) Data Center Family for PCIe* brings extreme data throughput directly to Intel® Xeon® processors with up to six times faster data transfer speed than 6 Gbps SAS/SATA SSDs¹. The Intel SSD DC Family for PCIe* is capable of reading data up to 2.8GB/s and 460k Input/Output Operations Per Second (IOPS) and writing up to 2.0GB/s and 175k IOPS.

The performance of a single drive from the Intel SSD DC Family for PCIe*, specifically the Intel® Solid-State Drive Data Center P3700 Series (460K IOPS), can replace the performance of 7 SATA SSDs aggregated through an HBA (~500K IOPS). At 200 IOPS per Hard Disk Drive (HDD), 2,300 15K HDDs would be needed to match the performance of one Intel SSD DC Family for PCIe* device.

Intel SSD DC Family for PCIe's* consistently amazing performance provides fast, unwavering data streams directly to Intel Xeon processors making server data transfers efficient. SSD performance consistency provides scalable throughput when multiple SSDs are unified into a single storage volume. The massive storage bandwidth increase feeds Intel Xeon processor systems giving data center servers a performance boost.

Proven Quality and Reliability

Intel® SSD Data Center Tool provides a powerful set of management capabilities.

Intel SSD Data Center Family for PCIe* devices are based on Intel-developed controller, firmware, and leading manufacturing process NAND flash memory. Rigorous qualification and compatibility testing ensures a highly reliable SSD. By combining SSD NAND management techniques and NAND silicon enhancements, High Endurance Technology (HET) enables the DC P3700 Series to achieve 10 drive writes per day over a 5 year drive life.

For more information, visit www.intel.com/design/flash/nand/managessd.htm

Modernizes Data Center Storage

Intel led the industry in creation of a new Non-Volatile Memory Express* storage interface standard.

Non-Volatile Memory Express* (NVMe*) is engineered for current and future Non-Volatile Memory (NVM) technologies, unlike SAS/SATA SSDs. NVMe* overcomes SAS/SATA SSD performance limitations by optimizing hardware and software to take full advantage of NVM SSD technology. Intel Xeon processors efficiently transfer data in fewer clock cycles with the NVMe* optimized software stack compared to the legacy Advance Host Controller Interface (AHCI) stack, reducing latency and overhead. Direct CPU connection also eliminates Host-Bus-Adapter (HBA) cards, further reducing latency and TCO.

Comprehensive Solution

Intel is driving transition to NVMe* SSDs by providing a comprehensive product line.

Intel's product line enables extensive system compatibility, completes numerous industry standard compliance certifications, and delivers Intel drivers, supporting industry driver development. The Intel SSD DC Family for PCIe* includes the Intel® Solid-State Drive Data Center P3700, P3600, and P3500 Series providing a full range of endurance up to 10 full-capacity writes per day, capacity up to 2TB, and 2.5" and Add-In-Card (AIC) form-factors. Intel-enabled NVMe* software drivers are provided by major operating system vendors including Microsoft* Server 2012 and 2008, Red Hat* 6.5, UEFI* 2.3.1, and the Linux* Open Source development community. The new 2.5" form-factor with hotswap capability provides convenient front panel serviceability allowing quick, uninterrupted installation. The AIC form-factor conveniently fits in half-height, half-length slots.

Solid-State Drive Computing Starts with Intel Inside®. For more information, visit www.intel.com/ssd

Intel® Solid-State Drive Data Center Family for PCIe*

| Technical Specifications ¹ | | | |
|--|--|---|----------------------------|
| Product Family | Intel® Solid-State Drive Data Center Family for PCIe* | | |
| Series Name | Intel® SSD DC P3500 Series | Intel® SSD DC P3600 Series | Intel® SSD DC P3700 Series |
| Capacities (GB) | 400, 1200, 2000 | 400, 800, 1200, 1600, 2000 | 400, 800, 1600, 2000 |
| Sequential Read | Up to 2500 | Up to 2600 | Up to 2800 |
| Sustained Write | Up to 1700 | Up to 1700 | Up to 2000 |
| Performance ^{2,3} (MB/s) | | | |
| Random I/O Read | Up to 450 | Up to 450 | Up to 460 |
| Operations Write | Up to 35 | Up to 56 | Up to 175 |
| 70/30 Read/Write | Up to 85 | Up to 160 | Up to 265 |
| per Second 4KB K-IOPS ^{2, 3} | | | |
| Lifetime Endurance ⁷ | Up to: 0.3 Drive Writes Per Day | 3 Drive Writes Per Day | 10 Drive Writes Per Day |
| Latency ⁴ Read/Write | 20μs / 20μs | | |
| Interface | Non-Volatile Memory express (NVMe*) PCIe* 3.0 x4 | | |
| Form Factor | 2.5 inch | AIC | |
| Height / Weight | 15mm/up to 125 grams | Half Height Half Length (HHHL) /195 grams | |
| Life Expectancy | 2 million hours Mean Time Between Failures (MTBF), 230 years | | |
| Power Consumption ⁵ | Active: <25W (Write) / <11W (Read) Idle: 4W Typical | | |
| NAND Flash Memory | Intel® NAND Flash Memory Multi-Level Cell (MLC) 20nm | | |
| Operating Temperature ⁶ | 2.5" FF: 0° C to 35° C ambient temperature with suggested airflow, 0° to 70° C case temperature AIC: 0° C to 55° C ambient temperature with suggested airflow | | |
| RoHS Compliance | Meets the requirements of European Union (EU) RoHS Compliance Directives | | |
| Software Support | Intel® Solid-State Drive Data Center Tool, NVMe* Drivers: www.intel.com | | |
| Product ordering | Solid-State Drive Computing Starts with Intel Inside®. To order visit www.intel.com/ssd | | |

- 1. Based on the Intel Solid-State Drive DC P3500, P3600 and P3700 Series Product Specifications. Random I/O Operations based on Thousand (K) IOPS
- 2. Performance varies by capacity and is measured using IOMeter* with Queue Depth 128, for sequential workload Queue Depth 128 with single worker. For Random workload Queue Depth 32, with 4 workers.
- 3. Measurements are performed on full span of logical block address (LBA) range on an SSD that is filled to capacity with data. IOPS setup: Intel® CoreTM i7-3770K CPU @ 3.50GHz, 8GB of system memory, Windows* Server 2012, and IOMeter* tool were used. DC P3700 system performance is configuration dependent. Random performance is collected with 4 workers each with 32 OD.
- Average latency measured with 4KB sequential I/O at Queue Depth 1
- 5. Active power measured during execution of Full Sequential Workload with 128KB transfer size, idle power is measured when there is no I/O to SSD.
- 6. For suggested airflow please refer to the product specification document.
- 7. Using JESD218 standard with JESD219 workload, Terabytes Written (TBW)
- 8. SAS/SATA 6 Gbps SSDs are limited to typical throughput up to 550MB/s and 80k IOPS

INFORMATION IN THIS DOCUMENT IS PROVIDED IN CONNECTION WITH INTEL® PRODUCTS. NO LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE, TO ANY INTELLECTUAL PROPERTY RIGHTS IS GRANTED BY THIS DOCUMENT. EXCEPT AS PROVIDED IN INTEL'S TERMS AND CONDITIONS OF SALE FOR SUCH PRODUCTS, INTEL ASSUMES NO LIABILITY WHATSOEVER, AND INTEL DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY, RELATING TO SALE AND/OR USE OF INTEL PRODUCTS INCLUDING LIABILITY OR WARRANTIES RELATING TO FITNESS FOR A PARTICULAR PURPOSE, MERCHANTABILITY, OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT. UNLESS OTHERWISE AGREED IN WRITING BY INTEL, THE INTEL PRODUCTS ARE NOT DESIGNED NOR INTENDED FOR ANY APPLICATION IN WHICH THE FAILURE OF THE INTEL PRODUCT COULD CREATE A SITUATION WHERE PERSONAL INJURY OR DEATH MAY OCCUR.

Intel may make changes to specifications and product descriptions at any time, without notice. Designers must not rely on the absence or characteristics of any features or instructions marked "reserved" or "undefined." Intel reserves these for future definition and shall have no responsibility whatsoever for conflicts or incompatibilities arising from future changes to them. The information here is subject to change without notice. Do not finalize a design with this information.

Software and workloads used in performance tests may have been optimized for performance only on Intel microprocessors. Performance tests, such as SYSmark and MobileMark, are measured using specific computer systems, components, software, operations and functions. Any change to any of those factors may cause the results to vary. You should consult other information and performance tests to assist you in fully evaluating your contemplated purchases, including the performance of that product when combined with other products.

Performance tests and ratings are measured using specific computer systems and/or components and reflect the approximate performance of Intel products as measured by those tests. Any difference in system hardware or software design or configuration may affect actual performance. Buyers should consult other sources of information to evaluate the performance of systems or components they are considering purchasing. For more information on performance tests and on the performance of Intel products, go to: http://www.intel.com/performance/resources/benchmark_limitations.htm.

The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request. Contact your local Intel sales office or your distributor to obtain the latest specifications and before placing your product order. Copies of documents which have an order number and are referenced in this document, or other Intel literature, may be obtained by calling 1-800-548-4725, or by visiting Intel's Web site at www.intel.com.

*Other names and brands may be claimed as the property of others.

Copyright © 2014 Intel Corporation. All rights reserved. Intel, the Intel logo, and Intel Inside are trademarks of Intel Corporation in the U.S. and other countries.

Printed in the USA 20141103 tlm 330591-002US